SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SDAS272A - NOVEMBER 1994 - REVISED JANUARY 2003

- 4.5-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 5.5 ns at 5 V

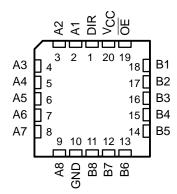
SN54ALS245A . . . J OR W PACKAGE SN54AS245 . . . J PACKAGE SN74ALS245A . . . DB, DW, N, OR NS PACKAGE SN74AS245 . . . DW, N, OR NS PACKAGE

> (TOP VIEW) 20 🛮 V_CC DIR [А1 [2 19 OE 18**∏** B1 A2 **∏**3 17 B2 A3 [16**∏** B3 А4 Г A5 [15**∏** B4 14**∏** B5 A6 [A7 **∏**8 13**∏** B6 A8 **∏**9 12 B7 GND [] 10 11 B8

3-State Outputs Drive Bus Lines Directly

pnp Inputs Reduce dc Loading

SN54ALS245A, SN54AS245 . . . FK PACKAGE (TOP VIEW)



description/ordering information

ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
			SN74ALS245A-1N	SN74ALS245A-1N	
	PDIP – N	Tube	SN74ALS245AN	SN74ALS245AN	
			SN74AS245N	SN74AS245N	
		Tube	SN74ALS245ADW	ALS245A	
		Tape and reel	SN74ALS245ADWR	AL3243A	
	SOIC - DW	Tube	ALS245A-1		
0°C to 70°C	SOIC - DW	Tape and reel SN74ALS245A-1DWR		AL3243A-1	
		Tube	SN74AS245DW	AS245	
		Tape and reel	SN74AS245DWR	A3245	
		Tape and reel SN74ALS		ALS245A	
	SOP – NS	Tape and reel	SN74ALS245A-1NSR	ALS245A-1	
	Tape and reel		SN74AS245NSR	74AS245	
	SSOP – DB	Tape and reel	SN74ALS245ADBR	G245A	
	CDIR	Tube	SNJ54ALS245AJ	SNJ54ALS245AJ	
	CDIP – J		SNJ54AS245J	SNJ54AS245J	
–55°C to 125°C	CFP – W	Tube	SNJ54ALS245AW	SNJ54ALS245AW	
	LCCC – FK	Tube	SNJ54ALS245AFK	SNJ54ALS245AFK	
	LOCC - FR	Tube	SNJ54AS245FK	SNJ54AS245FK	



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 **OCTAL BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS

SDAS272A - NOVEMBER 1994 - REVISED JANUARY 2003

description/ordering information(continued)

These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

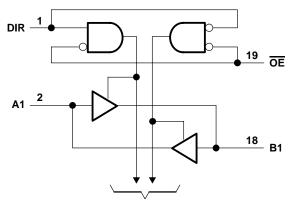
The devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction-control (DIR) input. The output-enable (OE) input can be used to disable the device so that the buses are effectively isolated.

The -1 version of the SN74ALS245A is identical to the standard version, except that the recommended maximum I_{OL} is increased to 48 mA. There is no -1 version of the SN54ALS245A.

FUNCTION TABLE

INP	UTS	OPERATION
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

logic diagram, each gate (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (SN54ALS245A, SN74ALS245A) (unless otherwise noted)†

Supply voltage, V _{CC}		7 V
Input voltage, V _I : All inputs		7 V
I/O ports		5.5 V
Package thermal impedance, θ _{JA} (see Note 1)	: DB package	70°C/W
-	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
Storage temperature range		. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 **ÓCTAL BUS TRÁNSCEIVERS** WITH 3-STATE OUTPUTS

SDAS272A - NOVEMBER 1994 - REVISED JANUARY 2003

recommended operating conditions (see Note 2)

		SNS	4ALS24	5A	SN7	4ALS24	5A	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-12			-15	mA
lo.	Low lovel output ourrent			12			24	mA
lor	Low-level output current						48†	IIIA
TA	Operating free-air temperature	-55		125	0		70	°C

† Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEST COL	IDITIONS	SN5	4ALS24	5A	SN7	'4ALS24	5A	LINUT
	PARAMETER	TEST CON	IDITIONS	MIN	TYP [‡]	MAX	MIN	TYP‡	MAX	UNIT
٧ıĸ		V _{CC} = 4.5 V,	I _I = -18 mA			-1.5			-1.5	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2)		
\ _{\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\}			$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V
∨он		V _{CC} = 4.5 V	$I_{OH} = -12 \text{ mA}$	2						V
			$I_{OH} = -15 \text{ mA}$				2			
			I _{OL} = 12 mA		0.25	0.4		0.25	0.4	
VOL		V _{CC} = 4.5 V	I _{OL} = 24 mA					0.35	0.5	V
			I _{OL} = 48 mA [†]					0.35	0.5	
1.	Control inputs	V-0 - 5 5 V	V _I = 7 V			0.1			0.1	mA
'	A or B ports	V _{CC} = 5.5 V	V _I = 5.5 V			0.1			0.1	ША
	Control inputs	V00 - 5 5 V	V: - 2.7.V			20			20	^
lΉ	A or B ports§	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
ī	Control inputs	Vaa 55V	V: 0.4.V			-0.1			-0.1	A
lı∟	A or B ports§	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
Io¶		V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
			Outputs high		30	48		30	45	
Icc		V _{CC} = 5.5 V	Outputs low		36	60		36	55	mA
			Outputs disabled		38	63		38	58	

 $^{^\}dagger$ Applies only to the -1 version and only if V_{CC} is between 4.75 V and 5.25 V



[‡] All typical values are $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.

The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, IOS.

SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 **OCTAL BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS

SDAS272A - NOVEMBER 1994 - REVISED JANUARY 2003

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT) A or B OE	TO (OUTPUT)	C _i R'	L = 50 pl 1 = 500 <u>9</u> 2 = 500 <u>9</u>	Ω,	V,	UNIT	
			SN54AL	S245A	SN74AL	.S245A		
			MIN	MAX	MIN	MAX		
t _{PLH}	A or P	B or A	1	19	3	10	ns	
^t PHL	AUD	BOIA	1	14	3	10	115	
^t PZH		A or B	2	30	5	20	ns	
t _{PZL}	OE	AOIB	2	29	5	20	115	
^t PHZ	ŌĒ	A or B	2	14	2	10	ns	
^t PLZ	OE	A OI D	2	30	4	15	115	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (SN54AS245, SN74AS245) (unless otherwise noted)

Supply voltage, V _{CC}	
Input voltage, V _I : All inputs	
I/O ports	5.5 V
Package thermal impedance, θ_{JA} (see Note 1): D	W package 58°C/W
N	l package 69°C/W
N	IS package 60°C/W
Storage temperature range	

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

		SI	N54AS24	5	SI	N74AS24	15	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V_{IL}	Low-level input voltage			8.0			0.8	V
I _{ОН}	High-level output current			-12			-15	mA
loL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	0	_	70	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245 **ÓCTAL BUS TRÁNSCEIVERS WITH 3-STATE OUTPUTS**

SDAS272A - NOVEMBER 1994 - REVISED JANUARY 2003

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	DADAMETED	TEST COL	UDITIONS	AS .	154AS24	15	SI	N74AS24	15	LIAUT
	PARAMETER	TEST CO	NDITIONS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNIT
٧ıK		$V_{CC} = 4.5 \text{ V},$	I _I = –18 mA			-1.2			-1.2	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	I _{OH} = −2 mA	V _{CC} -2	2		V _{CC} -2	2		
VOH			$I_{OH} = -3 \text{ mA}$	2.4	3.2		2.4	3.2		V
		$V_{CC} = 4.5 \text{ V}$	$I_{OH} = -12 \text{ mA}$	2						V
			$I_{OH} = -15 \text{ mA}$				2			
V0.		V _{CC} = 4.5 V	I _{OL} = 48 mA		0.3	0.55				V
VOL		VCC = 4.5 V	$I_{OL} = 64 \text{ mA}$					0.35	0.55	V
ļ	Control inputs	V _{CC} = 5.5 V	V _I = 7 V			0.1			0.1	mA
11	A or B ports	VCC = 5.5 V	V _I = 5.5 V			0.1			0.1	Ш
ļ	Control inputs	V _{CC} = 5.5 V,	V _I = 2.7 V			50			20	μΑ
ΊΗ	A or B ports [‡]	VCC = 5.5 v,	V - 2.7 V			70			70	μΛ
ļ	Control inputs	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.5			-0.5	mA
ΊL	A or B ports‡	VCC = 5.5 V,	V = 0.4 V			-0.75			-0.75	ША
ΙΟ§		$V_{CC} = 5.5 \text{ V},$	V _O = 2.25 V	-50		-150	-50		-150	mA
			Outputs high		62	97		62	97	
ICC		V _{CC} = 5.5 V	Outputs low		95	143		95	143	mA
			Outputs disabled		79	123		79	123	

switching characteristics (see Figure 1)

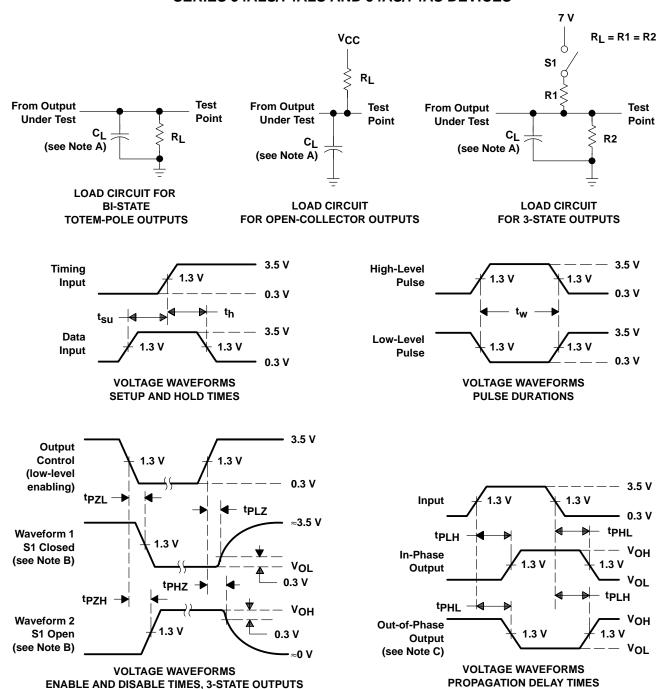
PARAMETER	FROM (INPUT)	TO (OUTPUT)	C _L R1 R2	= 50 pF = 500 \(\text{S} \)	2,	V,	UNIT
			SN54A	S245	SN74A	S245	
			MIN	MAX	MIN	MAX	
t _{PLH}	A or B	B or A	2	9.5	2	7.5	ns
^t PHL	AUID	BULK	2	9	2	7	115
^t PZH	ŌĒ	A or B	2	11	2	9	ns
tPZL	ÜE	AUID	2	10.5	2	8.5	115
^t PHZ	ŌĒ	A or B	2	7.5	2	5.5	ns
^t PLZ	UE	7010	2	12	2	9.5	115

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[†] All typical values are V_{CC} = 5 V, T_A = 25°C.
‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.
§ The output conditions have been chosen to produce a current that closely approximates one-half of the true short-circuit output current, I_{OS}.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 - D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_r = t_f = 2$ ns, duty cycle = 50%.
 - E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms







25-Sep-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)		(3)		(4/5)	
84030012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84030012A SNJ54ALS 245AFK	Samples
8403001RA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001RA SNJ54ALS245AJ	Samples
8403001SA	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	8403001SA SNJ54ALS245AW	Samples
SN54ALS245AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54ALS245AJ	Samples
SN54AS245J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SN54AS245J	Samples
SN74ALS245A-1DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245A-1N	Samples
SN74ALS245A-1NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245A-1N	Samples
SN74ALS245A-1NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1NSRE4	ACTIVE	so	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245A-1NSRG4	ACTIVE	so	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A-1	Samples
SN74ALS245ADBLE	OBSOLETI	SSOP	DB	20		TBD	Call TI	Call TI	0 to 70		



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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ALS245ADBR	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G245A	Samples
SN74ALS245ADBRE4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G245A	Samples
SN74ALS245ADBRG4	ACTIVE	SSOP	DB	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	G245A	Sample
SN74ALS245ADW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Samples
SN74ALS245ADWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Sample
SN74ALS245ADWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Sample
SN74ALS245ADWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Sample
SN74ALS245ADWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Sample
SN74ALS245AN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245AN	Sample
SN74ALS245AN3	OBSOLETI	PDIP	N	20		TBD	Call TI	Call TI	0 to 70		
SN74ALS245ANE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS245AN	Sample
SN74ALS245ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Sample
SN74ALS245ANSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Sample
SN74ALS245ANSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS245A	Sample
SN74AS245DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS245	Sample
SN74AS245DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS245	Sample
SN74AS245DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	AS245	Sample
SN74AS245DWR	OBSOLETI	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70	AS245	
SN74AS245DWRE4	OBSOLETI	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		
SN74AS245DWRG4	OBSOLETI	SOIC	DW	20		TBD	Call TI	Call TI	0 to 70		





25-Sep-2013

Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)		(3)		(4/5)	
SN74AS245N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS245N	Samples
SN74AS245NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74AS245N	Samples
SN74AS245NSR	ACTIVE	so	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS245	Samples
SN74AS245NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS245	Samples
SN74AS245NSRG4	ACTIVE	so	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74AS245	Samples
SNJ54ALS245AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84030012A SNJ54ALS 245AFK	Samples
SNJ54ALS245AJ	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403001RA SNJ54ALS245AJ	Samples
SNJ54ALS245AW	ACTIVE	CFP	W	20	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	8403001SA SNJ54ALS245AW	Samples
SNJ54AS245FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	SNJ54AS 245FK	Samples
SNJ54AS245J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type	-55 to 125	SNJ54AS245J	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

25-Sep-2013

- (3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54ALS245A, SN54AS245, SN74ALS245A, SN74AS245:

Catalog: SN74ALS245A, SN74AS245

Military: SN54ALS245A, SN54AS245

NOTE: Qualified Version Definitions:

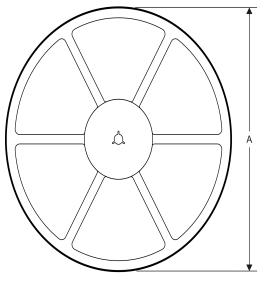
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

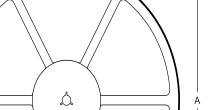
PACKAGE MATERIALS INFORMATION

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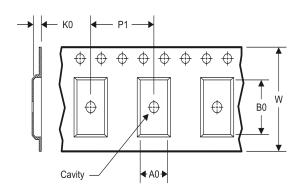
TAPE AND REEL INFORMATION

REEL DIMENSIONS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS245A-1DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS245A-1NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74ALS245ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ALS245ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
SN74ALS245ANSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1
SN74AS245NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1

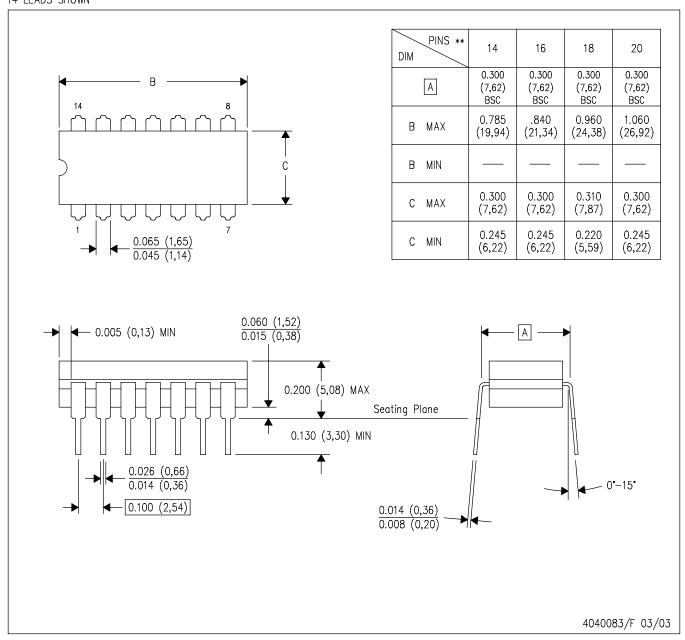
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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS245A-1DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS245A-1NSR	SO	NS	20	2000	367.0	367.0	45.0
SN74ALS245ADBR	SSOP	DB	20	2000	367.0	367.0	38.0
SN74ALS245ADWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ALS245ANSR	SO	NS	20	2000	367.0	367.0	45.0
SN74AS245NSR	SO	NS	20	2000	367.0	367.0	45.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



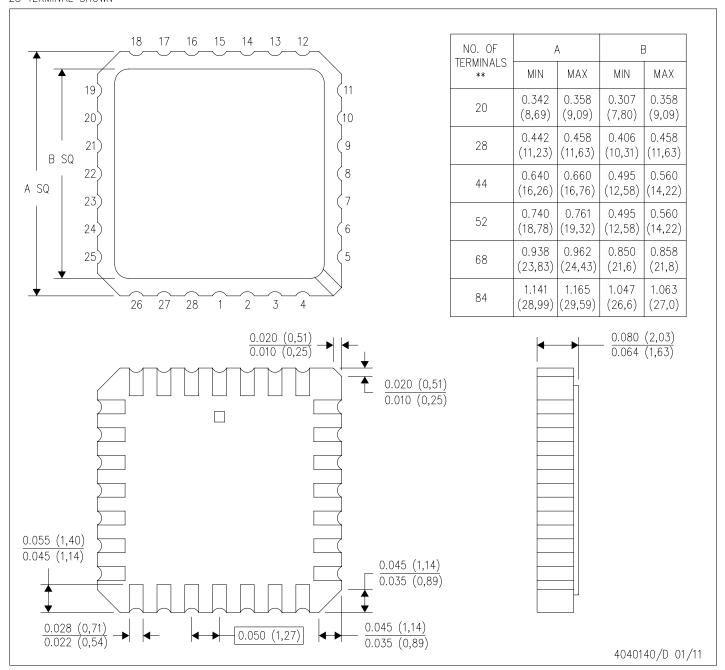
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



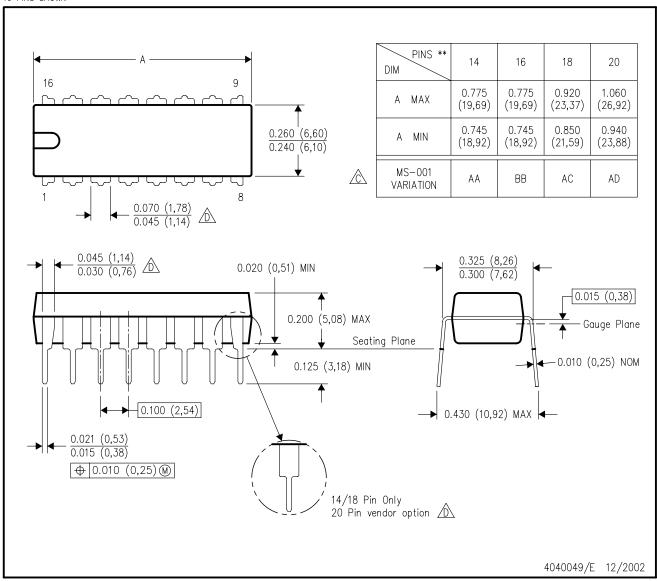
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



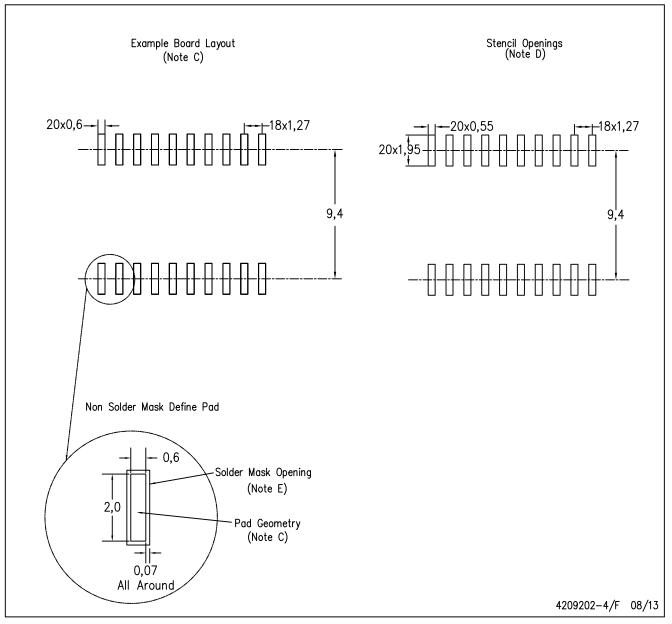
NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

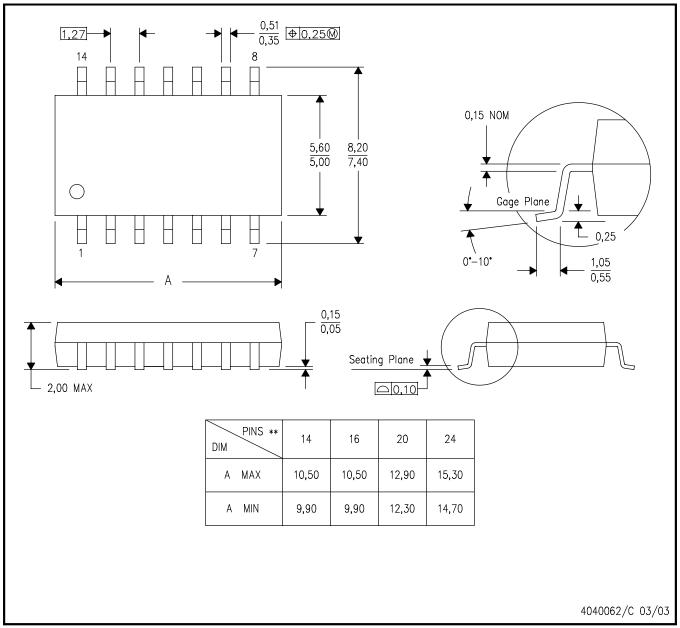


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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